

:1-3

L8 ANSWER 1 OF 3 INPADOC COPYRIGHT 1996 EPO FAMILY 1  
AN 15721317 INPADOC EW 8928 UP 890722  
TI MANUFACTURE OF SEMICONDUCTOR DEVICE.  
IN FUJIMOTO HIROAKI; HATADA KENZO  
INS FUJIMOTO HIROAKI; HATADA KENZO  
PA MATSUSHITA ELECTRIC IND CO LTD  
PAS MATSUSHITA ELECTRIC IND CO LTD  
DT Patent  
PIT JPA2 DOCUMENT LAID OPEN TO PUBLIC INSPECTION  
PI JP 64002331 A2 890106  
AI JP 87-158226 A 870625  
PRAI JP 87-158226 A 870625  
OSDW 89-051575  
OSJP 130168E000164

L8 ANSWER 2 OF 3 WPIDS COPYRIGHT 1996 DERWENT INFORMATION LTD  
FAMILY 1  
AN 89-051575 [07] WPIDS  
TI Mounting of LSI chips - by applying resin to connect semiconductor  
wafer to wiring board, by spin coating before dividing into chips  
NoAbstract Dwg 0/3.  
DC A85 L03 U11 U14  
PA (MATU) MATSUSHITA ELEC IND CO LTD  
CYC 1  
PI JP 64002331 A 890106 (8907)\* 4 pp <--  
ADT JP 64002331 A JP 87-158226 870625  
PRAI JP 87-158226 870625  
IC H01L021-60

L8 ANSWER 3 OF 3 JAPIO COPYRIGHT 1996 JPO and JapioFAMILY 1  
AN 89-002331 JAPIO  
TI MANUFACTURE OF SEMICONDUCTOR DEVICE  
IN FUJIMOTO HIROAKI; HATADA KENZO  
PA MATSUSHITA ELECTRIC IND CO LTD, JP (CO 000582)  
PI \*\*\*JP 64002331\*\*\* A 19890106 Showa  
AI JP 87-158226 (JP62158226 Showa) 19870625  
SO PATENT ABSTRACTS OF JAPAN, Unexamined Applications, Section: E,  
Sect. No. 747, Vol. 13, No. 168, P. 164 (19890421)  
IC ICM (4) H01L021-60

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